

General Purpose Photoresist Spin Coat

Operating Procedures [LINK](#)



Process Description:

For reproducible lithography, the photoresist needs to be uniform and pinhole-free. The standard method of application is spinning. In this method, the substrate is mounted on a vacuum chuck; a metered amount of photoresist is deposited onto the center of the wafer; and then the revolutions of wafer flings off the excess resist and a uniform film is produced. Viscosity of the photoresist, rotational speed and time of the spin are the controlling parameters.

Equipment Description:

The Headway spinners are capable of coating substrates up to 8 inches in diameter. A variety of chuck holders are available. The programmable control unit holds 10 spin recipes. Each recipe step is programmed with variable spin speeds up to 10,000 rpm, spin ramp rates and step time duration.